

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention	[MOLD AND METHOD OF MOLDING SEMICONDUCTOR DEVICES]				
Application Number :					
Date :					
First Named Applicant:	Mr. Jen-Chieh Kao				
Attorney Docket Number:	11184-US-PA				
TOTAL FEE AUTHORIZED \$ 810					
Patent fees are subject to annual revisions on or about October 1st of each year.					
Filing as large entity					
BASIC FILING FEE					
Fee Description	Fee Code	Amount \$	Fee Paid \$		
Utility Filing Fee	1001	770	770		
Subtotal For Basic Filing Fees: \$ 770					
EXTRA CLAIM FEES					
Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$	
Total Claims : 19	0	1202	18	0	
Independent Claims : 3	0	1201	86	0	
Subtotal For Extra Claims Fees: \$ 0					
ASSIGNMENT FEES					
Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					
AUTHORIZED BILLING INFORMATION					
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:					
Credit account number:	1007				
Expiration Date (YYYYMMDD):	2005-12-31				
Authorized name:	YEH, WEN-HUNG				
Billing address:	99999				